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Smart Sensors, Actuators, and MEMS IV

**Ulrich Schmid
Carles Cané
Herbert Shea**
Editors

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Contents

xi	Conference Committee
xv	Introduction

ENERGY SCAVENGERS

- 7362 02 **Coupled piezoelectric-circuit FEA to study influence of a resistive load on power output of piezoelectric energy devices** [7362-01]
M. Zhu, E. Worthington, J. Njuguna, Cranfield Univ. (United Kingdom)
- 7362 03 **Increasing sensitivity of vibration energy harvester** [7362-02]
Z. Hadas, C. Ondrusek, V. Singule, Brno Univ. of Technology (Czech Republic)
- 7362 04 **Analytical characterization and experimental validation of performances of piezoelectric vibration energy scavengers** [7362-03]
E. Brusa, Politecnico di Torino (Italy); S. Zelenika, Univ. of Udine (Croatia) and Univ. of Rijeka (Croatia); L. Moro, D. Benasciutti, Univ. of Udine (Italy)
- 7362 05 **Thermoelectric thin film power generators: self-sustaining power supply for smart systems** [7362-04]
J. Nurnus, Micropelt GmbH (Germany)

BIOSENSORS

- 7362 06 **New transducer material concepts for biosensors and surface functionalization (Invited Paper)** [7362-05]
A. Lloyd Spetz, R. Pearce, L. Hedin, V. Khranovskyy, F. Söderlind, P.-O. Käll, R. Yakimova, K. Uvdal, Linköping Univ. (Sweden)
- 7362 07 **Fast detection of air contaminants using immunobiological methods** [7362-06]
K. Schmitt, C. Bolwien, G. Sulz, Fraunhofer Institute for Physical Measurement Technique (Germany); W. Koch, W. Dunkhorst, H. Lödding, K. Schwarz, Fraunhofer Institute of Toxicology and Experimental Medicine (Germany); A. Holländer, Fraunhofer Institute for Applied Polymer Research (Germany); T. Klockenbring, S. Barth, B. Seidel, Fraunhofer Institute for Molecular Biology and Applied Ecology (Germany); W. Hofbauer, T. Rennebarth, A. Renzl, Fraunhofer Institute for Building Physics (Germany)
- 7362 08 **Sputtered polycrystalline AlN as a platform for biofunctionalized devices** [7362-07]
M. J. Oliver, J. Hernando, Univ. de Castilla-La Mancha (Spain); J. Olivares, M. Clement, Univ. Politécnica de Madrid (Spain); A. Ababneh, Saarland Univ. (Germany); U. Schmid, Vienna Univ. of Technology (Austria); J. L. Sánchez-Rojas, Univ. de Castilla-La Mancha (Spain)

RESONANT MEMS

- 7362 0A **Analysis of the quality factor of piezoelectric-actuated micro-resonators** [7362-09]
T. Manzaneque, J. Hernando, J. Rodríguez-Aragón, Univ. de Castilla-La Mancha (Spain);
A. Ababneh, H. Seidel, Saarland Univ. (Germany); U. Schmid, Vienna Univ. of Technology
(Austria); J. L. Sánchez-Rojas, Univ. de Castilla-La Mancha (Spain)
- 7362 0B **An envelope model to describe the sensor dynamics of vibratory gyroscopes** [7362-10]
M. Egretzberger, A. Kugi, Vienna Univ. of Technology (Austria)

PACKAGING

- 7362 0C **Manufacturing, assembling and packaging of miniaturized implants for neural prostheses and brain-machine interfaces (Invited Paper)** [7362-11]
T. Stieglitz, Univ. of Freiburg (Germany)
- 7362 0D **Packaging of MEMS microphones** [7362-12]
G. Feiertag, EPCOS AG (Germany); M. Winter, Univ. des Saarlandes (Germany) and EPCOS
AG (Germany); A. Leidl, EPCOS AG (Germany)
- 7362 0E **Adhesive wafer bonding using photosensitive polymer layers** [7362-13]
V. Dragoi, EV Group E. Thallner GmbH (Austria); E. Cakmak, EV Group Inc. (United States);
E. Capsuto, C. McEwen, Shin-Etsu MicroSi Inc. (United States); E. Pabo, EV Group Inc. (United
States)

POLYMER DEVICES

- 7362 0F **Voltage tuning of the resonance frequency of electroactive polymer membranes over a range of more than 75%** [7362-14]
P. Dubois, S. Rosset, M. Niklaus, H. Shea, Ecole Polytechnique Fédérale de Lausanne
(Switzerland)
- 7362 0G **Tactile sensors based on conductive polymers** [7362-15]
J. Castellanos-Ramos, R. Navas-Gonzalez, Univ. de Málaga (Spain); H. Macicior,
E. Ochoteco, CiDETEC (Spain); F. Vidal-Verdú, Univ. de Málaga (Spain)
- 7362 0H **A new concept for dielectric elastomer actuators: hydrostatic coupling** [7362-16]
F. Carpi, G. Frediani, D. De Rossi, Univ. di Pisa (Italy)
- 7362 0I **Ionic polymer-metal composites (IPMCs) containing Cu/Ni electrodes and ionic liquids for durability** [7362-17]
H.-K. Lee, N.-J. Choi, S. Jung, K.-H. Park, J. Kim, Electronics and Telecommunications
Research Institute (Korea, Republic of)

PIEZOELECTRIC MEMS

- 7362 0J **Aluminium nitride: a promising and full CMOS compatible piezoelectric material for MOEMS applications** [7362-18]
H. Conrad, Technische Univ. Dresden (Germany); J. U. Schmidt, W. Pufe, F. Zimmer, T. Sandner, H. Schenk, Fraunhofer Institute for Photonic Microsystems (Germany); H. Lakner, Technische Univ. Dresden (Germany) and Fraunhofer Institute for Photonic Microsystems (Germany)
- 7362 0K **Characterization and simulation of high-quality AlN-actuated resonant suspended beams** [7362-19]
J. Hernando, J. L. Sánchez-Rojas, Univ. de Castilla-La Mancha (Spain); A. Ababneh, H. Seidel, Saarland Univ. (Germany); Ü. Sökmen, E. Peiner, Braunschweig Univ. of Technology (Germany); U. Schmid, Vienna Univ. of Technology (Austria)
- 7362 0L **What happens turning a 250µm thin piezo-stack sideways? An experimental and analytical approach to one-side-actuated piezoelectric micro drives, regarding electrode layouts and directions of deflection** [7362-20]
S. Zähringer, N. Schwesinger, Technische Univ. München (Germany)
- 7362 0M **Robust superelastic, metallic amplification unit for piezoelectric microactuators** [7362-21]
C. Bolzmacher, K. Bauer, EADS Innovation Works Germany (Germany); U. Schmid, Vienna Univ. of Technology (Austria); M. Hafez, Commissariat à l'Energie Atomique (France); H. Seidel, Saarland Univ. (Germany)

RELIABILITY

- 7362 0N **New methods and instrumentation for functional, yield and reliability testing of MEMS on device, chip and wafer level (Invited Paper)** [7362-22]
I. De Wolf, IMEC (Belgium) and Katholieke Univ. Leuven (Belgium); J. De Coster, V. Cherman, IMEC (Belgium); P. Czarnecki, S. Kalicinski, IMEC (Belgium) and Katholieke Univ. Leuven (Belgium); O. Varela Pedreira, IMEC (Belgium); S. Sangameswaran, IMEC (Belgium) and Katholieke Univ. Leuven (Belgium); K. Vanstreels, IMEC (Belgium)
- 7362 0O **Single crystalline silicon-based surface micromachining for high-precision inertial sensors: technology and design for reliability** [7362-23]
R. Knechtel, X-FAB Semiconductor Foundries AG (Germany)
- 7362 0P **Reliability of Ag thin films sputter deposited on silicon and ceramic based substrates** [7362-24]
A. Bittner, S. Klein, H. Seidel, Saarland Univ. (Germany); U. Schmid, Vienna Univ. of Technology (Austria)

CHEMICAL SENSORS

- 7362 0Q **FIB generated antimony nanowires as chemical sensors** [7362-25]
A. Lugstein, A. Avdic, E. Bertagnolli, Vienna Univ. of Technology (Austria)

- 7362 OS **Fast transient temperature operating micromachined emitter for mid-infrared for optical gas sensing systems** [7362-27]
J. Hildenbrand, C. Peter, F. Lamprecht, A. Kürzinger, Fraunhofer Institute for Physical Measurement Technique (Germany); F. Naumann, M. Ebert, R. Wehrspohn, Fraunhofer Institute for Mechanics of Materials (Germany); J. Wöllenstein, Fraunhofer Institute for Physical Measurement Technique (Germany)

MATERIALS

- 7362 OU **Tuned wettability of material surfaces for tribological applications in miniaturized systems by laser interference metallurgy** [7362-29]
C. Gachot, M. Hans, R. Catrin, Saarland Univ. (Germany); U. Schmid, Technical Univ. (Austria); F. Mücklich, Saarland Univ. (Germany)
- 7362 OV **Electrical and mechanical characterization of low temperature co-fired ceramics for high temperature sensor applications** [7362-30]
C. Bienert, A. Roosen, Friedrich-Alexander-Univ. Erlangen-Nürnberg (Germany); M. Grosser, M. Ziegler, Univ. des Saarlandes (Germany); U. Schmid, Technische Univ. Wien (Austria)
- 7362 OW **New perspectives for pressure and force sensors thin films combining high gauge factor and low TCR** [7362-31]
G. Schultes, R. Koppert, D. Goettel, O. Freitag-Weber, A. C. Probst, HTW des Saarlandes (Germany); U. Werner, Leibniz-Institut fuer Neue Materialien GmbH (Germany)
- 7362 OX **Silicon oxide sacrificial layers deposited by pulsed-DC magnetron sputtering for MEMS applications** [7362-32]
S. González-Castilla, J. Olivares, M. Clement, Univ. Politécnica de Madrid (Spain); L. Vergara, Consejo Superior de Investigaciones Científicas (Spain); L. Pulido, E. Iborra, J. Sangrador, Univ. Politécnica de Madrid (Spain)

OPTICAL SYSTEMS

- 7362 OY **3.0-3.7 μ m infrared sensor system for cell analysis** [7362-33]
S. van den Driesche, Vienna Univ. of Technology (Austria); W. Witariski, Slovak Academy of Sciences (Slovakia); M. J. Vellekoop, Vienna Univ. of Technology (Austria)
- 7362 IO **Silicon comb-drive X-Y microstage with frame-in-the-frame architecture for MOEMS applications** [7362-35]
K. Laszczyk, S. Bargiel, FEMTO-ST, CNRS, Univ. de Franche-Comté (France); J. Krezel, Warsaw Univ. of Technology (Poland); C. Gorecki, FEMTO-ST, CNRS, Univ. de Franche-Comté (France); M. Kujawińska, Warsaw Univ. of Technology (Poland)
- 7362 II **Design and fabrication of self-assembling micromirror arrays** [7362-36]
Q. Li, A. Jäkel, V. Viereck, J. Schmid, H. Hillmer, Univ. of Kassel (Germany)

POSTER SESSION

- 7362 12 **Position encoding and closed loop control of MOEMS translatory actuators** [7362-37]
M. Lenzhofer, A. Tortschanoff, A. Frank, Carinthian Tech Research AG (Austria); T. Sandner, H. Schenk, Fraunhofer Institute for Photonic Microsystems (Germany); M. Kraft, A. Kenda, Carinthian Tech Research AG (Austria)
- 7362 13 **ICP cryogenic dry etching for shallow and deep etching in silicon** [7362-38]
Ü. Sökmén, M. Balke, A. Stranz, S. Fündling, E. Peiner, H.-H. Wehmann, A. Waag, Braunschweig Univ. of Technology (Germany)
- 7362 14 **A method for improving the drop test performance of a MEMS microphone** [7362-39]
M. Winter, Univ. des Saarlandes (Germany); S. Ben Aoun, Technische Univ. München (Germany); G. Feiertag, A. Leidl, P. Scheele, EPCOS AG (Germany); H. Seidel, Univ. des Saarlandes (Germany)
- 7362 15 **Test-bed for the remote health monitoring system for bridge structures using FBG sensors** [7362-40]
C.-H. Lee, K.-T. Park, B.-C. Joo, Y.-K. Hwang, Korea Institute of Construction Technology (Korea, Republic of)
- 7362 16 **Influence of back pressure and plasma power on grain size, phase composition and resistivity of tantalum thin films** [7362-41]
M. Grosser, Saarland Univ. (Germany); U. Schmid, Vienna Univ. of Technology (Austria)
- 7362 17 **Selective wet chemical etching of metallic thin films designed by laser interference metallurgy (LIMET)** [7362-42]
R. Catrin, C. Gachot, G. Marchand, Saarland Univ. (Germany); U. Schmid, Vienna Univ. of Technology (Austria); F. Mücklich, Saarland Univ. (Germany)
- 7362 18 **Piezoresistive chemical sensors based on hydrogels** [7362-43]
M. Guenther, G. Gerlach, Technische Univ. Dresden (Germany); T. Wallmersperger, Univ. Stuttgart (Germany)
- 7362 19 **Deformation measurements of high-speed MEMS with sub-picosecond pulses using combined digital holographic two-wavelength contouring and single phase reconstruction** [7362-44]
T. Hansel, U. Griebner, Max-Born-Institute for Nonlinear Optics and Short Pulse Spectroscopy (Germany); J. Bonitz, C. Kaufmann, Chemnitz Univ. of Technology (Germany)
- 7362 1A **High-resolution eddy current sensor system** [7362-45]
M. H. Schulze, H. Heuer, M. Küttner, Fraunhofer-Institut für Zerstörungsfreie Prüfverfahren (Germany)
- 7362 1B **Fabrication and characterization of yttria-stabilized zirconia membranes for micro solid oxide fuel cells** [7362-46]
Í. Garbayo, A. Tarancón, Ctr. Nacional de Microelectrónica, CSIC (Spain); J. Santiso, A. Cavallaro, J. Roqueta, CIN2, CSIC (Spain); G. Garcia, GFMI, Autonomous Univ. of Barcelona (Spain); I. Gràcia, C. Cané, N. Sabaté, Ctr. Nacional de Microelectrónica, CSIC (Spain)

- 7362 1D **RF MEMS switches based on an alloy of aluminum-silicon-copper** [7362-48]
S. Klein, C. Comtesse, A. Bittner, H. Seidel, Saarland Univ. (Germany); V. Ziegler, U. Prechtel, EADS Innovation Works (Germany); U. Schmid, Vienna Univ. of Technology (Austria)
- 7362 1E **Micromechanical sensors based on lateral and longitudinal displacement of a cantilever sensing element: a comparative performance study** [7362-49]
J. Matović, Technische Univ. Wien (Austria); Z. Jakšić, Univ. of Belgrade (Serbia)
- 7362 1F **Adsorption-desorption noise in plasmonic chemical/biological sensors in multiple analyte environment** [7362-50]
O. Jakšić, Nikola Tesla School of Electrical Engineering (Serbia); Z. Jakšić, Univ. of Belgrade (Serbia); J. Matović, Technische Univ. Wien (Austria)
- 7362 1G **Ultrasonic motor model and power analysis for industrial mobile applications** [7362-51]
J. Teichler, IAV GmbH (Germany); R. Chladny, ABB AG Corporate Research (Germany); C. Schroll, ZF Lenksysteme GmbH (Germany)
- 7362 1H **Motion planning for an adaptive wing structure with macro-fiber composite actuators** [7362-52]
J. Schröck, T. Meurer, A. Kugi, Vienna Univ. of Technology (Austria)
- 7362 1J **Novel measurement and monitoring system for forming processes based on piezoresistive thin film systems** [7362-54]
S. Biehl, S. Staufenberg, F. Hauschild, Fraunhofer Institute for Surface Engineering and Thin Films (Germany)
- 7362 1L **Growth of ZnO nanorods on patterned templates for energy harvesting applications** [7362-57]
G. Niarchos, E. Makarona, C. Tsamis, National Ctr. for Scientific Research "Demokritos" (Greece)
- 7362 1M **Characterisation of the intrinsic stress in micromachined parylene membranes** [7362-58]
T. Zöpfl, S. Klare, G. Wachutka, G. Schrag, Technische Univ. München (Germany)
- 7362 1N **Comparison between AlN thin films with different crystal orientations for MEMS applications** [7362-59]
A. Ababneh, G. Marchand, H. Seidel, Saarland Univ. (Germany); J. Hernando, J. L. Sánchez-Rojas, Univ. de Castilla, La Mancha (Spain); Ü. Sökmen, E. Peiner, Braunschweig Univ. of Technology (Germany); U. Schmid, Vienna Univ. of Technology (Austria)
- 7362 1P **Design, fabrication and characterization of a micro-fluxgate intended for parallel robot application** [7362-61]
M. R. Kirchhoff, G. Bogdanski, S. Büttgenbach, Technische Univ. Braunschweig (Germany)
- 7362 1Q **SAW-grade SiO₂ for advanced microfluidic devices** [7362-62]
A. Winkler, S. Menzel, H. Schmidt, IFW Dresden (Germany)

- 7362 1S **Power management circuit for resonant energy harvesters** [7362-64]
T. Jirků, M. Steinbauer, Brno Univ. of Technology (Czech Republic); M. Kluge, EADS
Deutschland GmbH (Germany)

Author Index

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Introduction

The conference 'Smart Sensors, Actuators and MEMS' took place in Dresden, Germany, from May 4th to May 6th, 2009. About 60 contributions from Europe, America and Asia were accepted and grouped into 11 sessions including a poster session. The interdisciplinary spirit of the event was displayed by a wide range of topics based on the latest results which were achieved in the research and development areas of precision engineering and MEMS. Therefore, sessions focused on material and fabrication aspects, on micromachined sensors for the determination of biological, physical and chemical quantities as well as on reliability issues. Furthermore, novel approaches for actuators, optical and RF MEMS were presented and more application oriented topics such as microfluidic systems, energy scavengers and low power management systems, were discussed. Due to this broad range of topics, researchers coming from academia and industry, with their specific backgrounds, created a very stimulating atmosphere for the exchange of new ideas.

Besides the high quality of the oral and poster presentations, I would like to highlight the 3 invited talks. The first was given by Anita Lloyd Spetz (Linköping University, Sweden) on new transducer material concepts for biosensors and surface functionalization. Thomas Stieglitz (University of Freiburg, Germany) gave a presentation on the manufacturing, assembling and packaging of miniaturized implants for neural prostheses and brain-machine interface. Last but not least, Ingrid De Wolf (IMEC, Belgium) gave a talk on new methods and instrumentation for functional, yield and reliability testing of MEMS on device, chip and wafer level.

I would like to thank all participants for their individual contributions which made the conference a successful event in the international conference calendar. Special thanks go to José Fco. López, Gerhard Krötz and Thomas Becker for organising the symposium, SPIE staff, and to my Co-Chairs Carles Cane and Herbert Shea. Finally, I would like to thank the Programme Committee for doing the reviews and acting partly as session chairs.

Ulrich Schmid